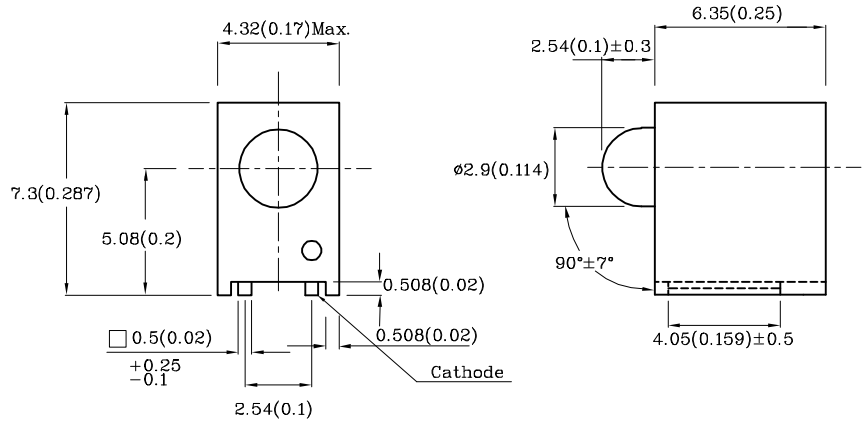


Features

- Black casing provides superior contrast
- Reliable & robust
- Standard Package: 500pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- Housing UL rating:94V-0.
- Housing material: PPA
- High temperature resistant housing.
- High glass transition temperature epoxy.
- RoHS compliant.



Package Schematics



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

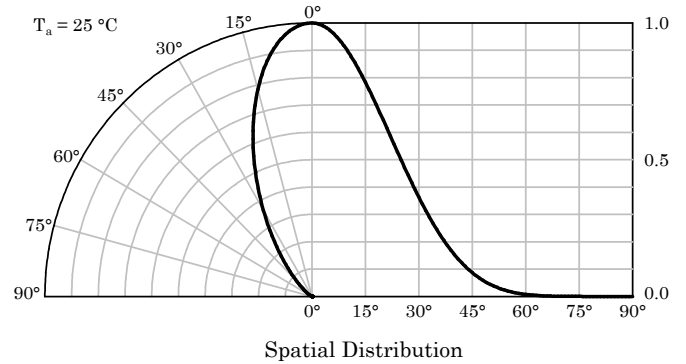
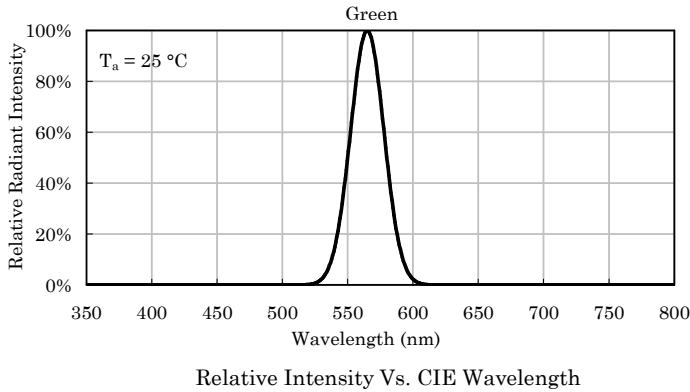
Absolute Maximum Ratings (T _A =25°C)		Green (GaP)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	140	mA
Power Dissipation	P _D	62.5	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

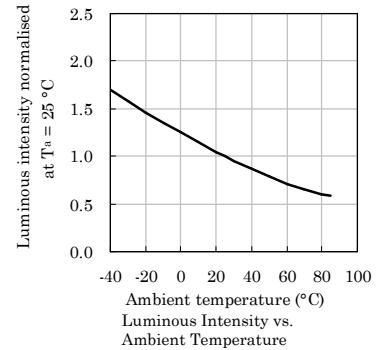
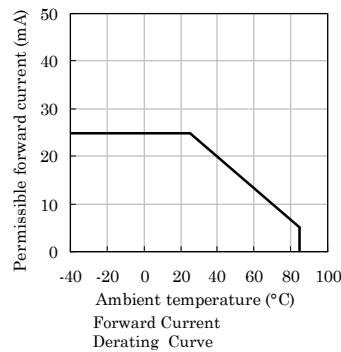
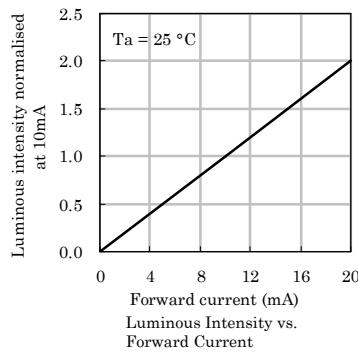
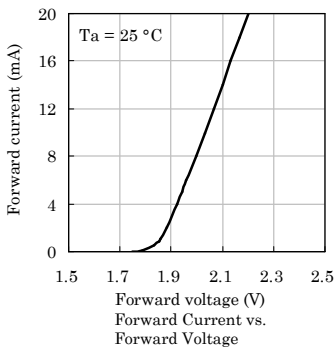
Operating Characteristics (T _A =25°C)		Green (GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V _F	2	V
Forward Voltage (Max.) (I _F =10mA)	V _F	2.4	V
Reverse Current (Max.) (V _R =5V)	I _R	10	µA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λ _P	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λ _D	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I _F =10mA) mcd		Wavelength CIE127-2007* nm λ _P	Viewing Angle 2θ 1/2
				min.	typ.		
XNK1LUG11DSMD	Green	GaP	Green Diffused	10*	24*	565*	50°

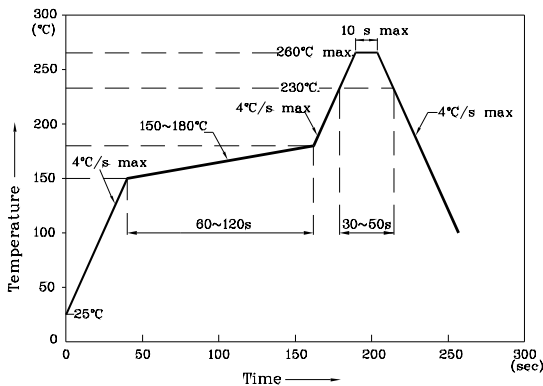
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



❖ Green



Reflow Soldering Profile for SMD Products (Pb-Free Components)



NOTES:

1. We recommend the reflow temperature 245 $^\circ\text{C}$ (+/-5 $^\circ\text{C}$). The maximum soldering temperature should be limited to 260 $^\circ\text{C}$.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. No more than once.

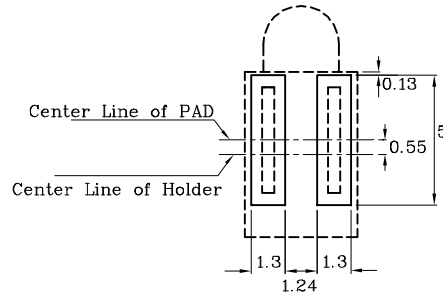
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

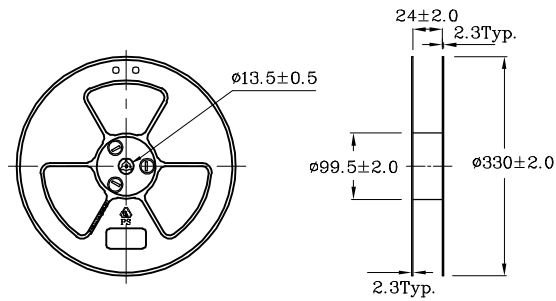
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

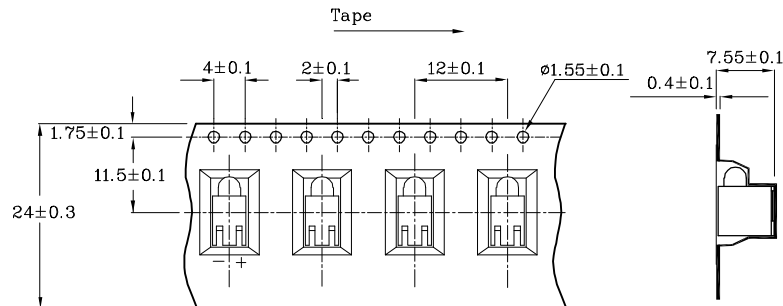
❖ Recommended Soldering Pattern
(Units: mm ; Tolerance: ± 0.1)



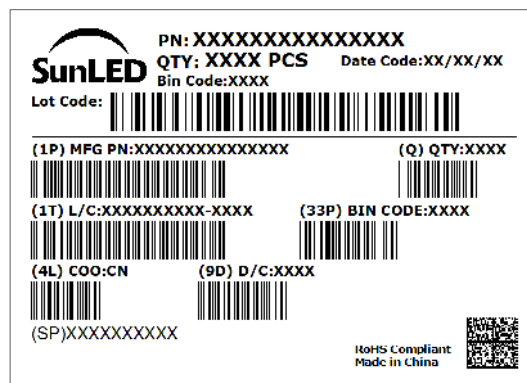
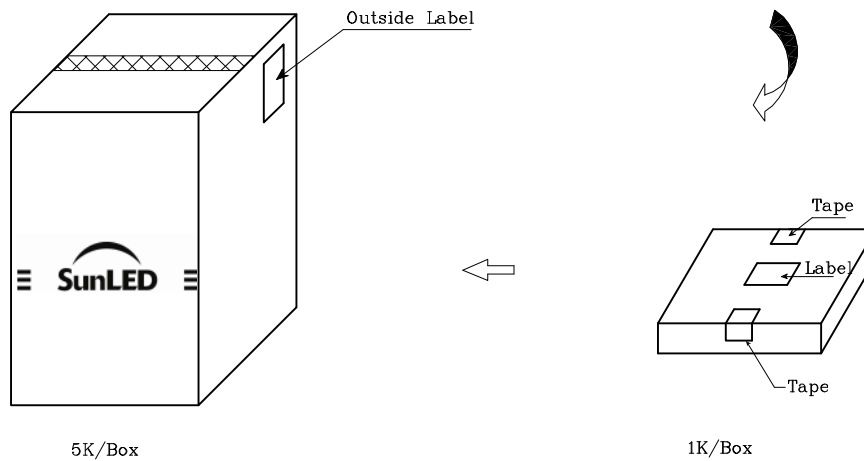
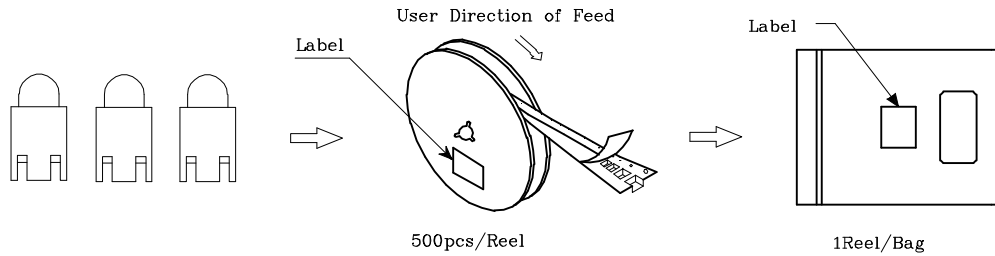
❖ Reel Dimension (Units : mm)



❖ Tape Specification (Units : mm)



PACKING & LABEL SPECIFICATIONS



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